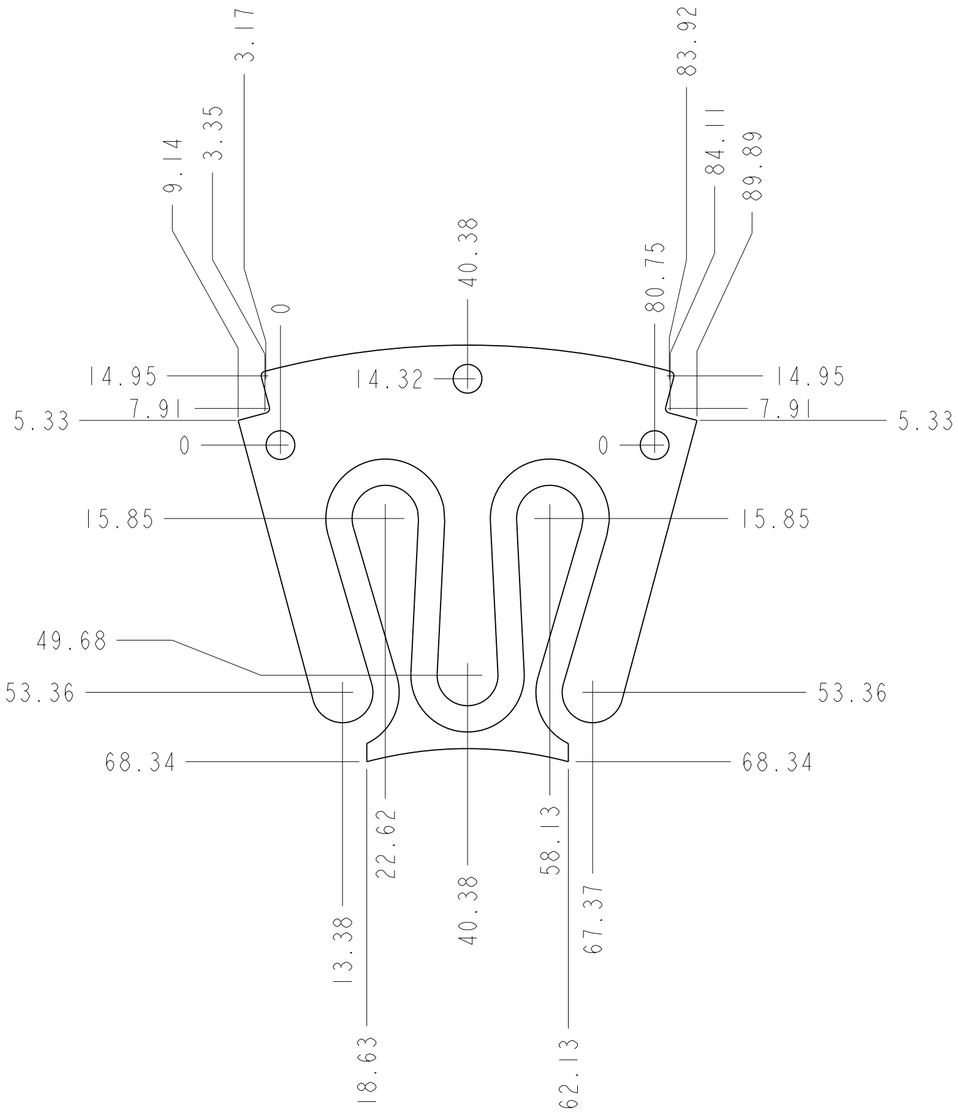
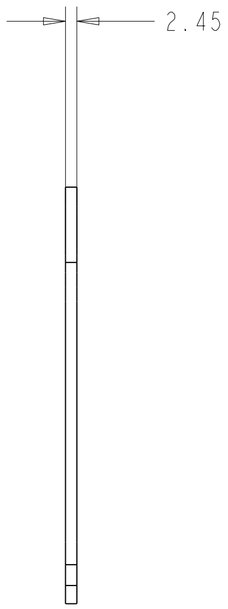
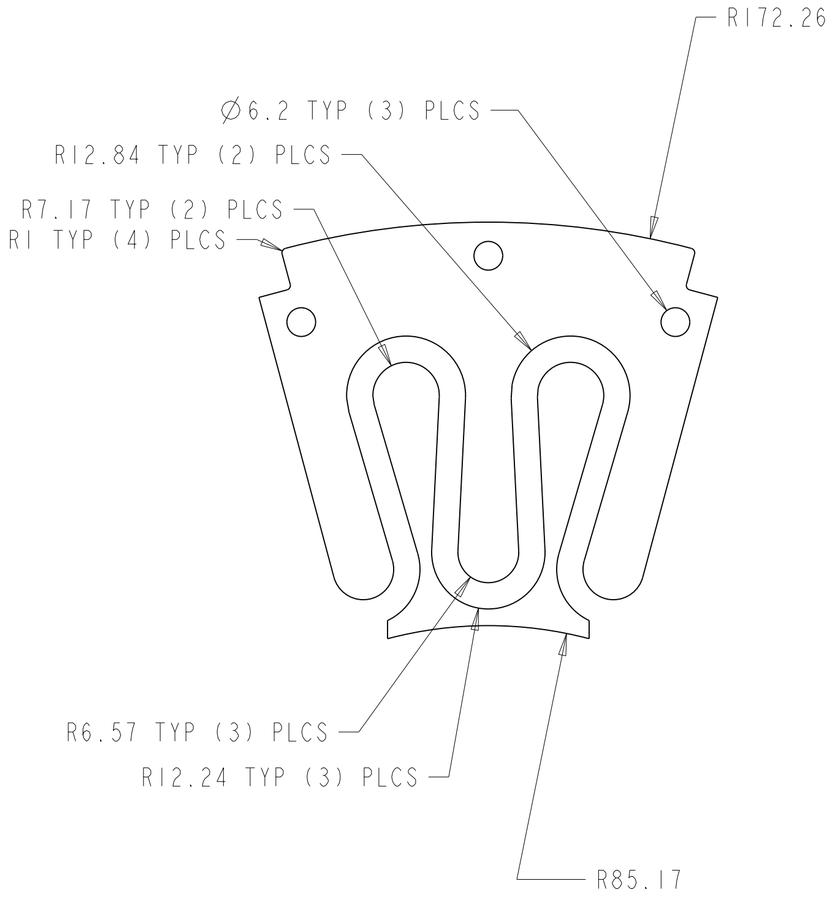
DESCRIPTION	MATERIAL	MAT. LOCATION
	BRYTE E01189-2M	-







REV	DWG	CHK	ZONE	DATE	CHANGES

UNLESS OTHERWISE SPECIFIED

TOLERANCES		
	X.X ± 0.1	FRAC. ± 1/64
	X.XX ± 0.01	Angles ± 0.50°
	X.XXX ± 0.001	FINISH 125 √(µin)

DO NOT SCALE PRINT

THREADS ARE CLASS 2

CHAMFER ENDS OF ALL SCREW TREADS 30°

CUT ROUND, 1.5 THREAD RELIEF ON MACHINED THREADS

BREAK EDGES .016 MAX. ON MACHINED WORK

REMOVE BURRS, WELD SPLATTER & LOOSE SCALE

IN ACCORDANCE WITH ASME Y14.5M & B46.1

SHOP ORDERS

SER NO.	-		
ACCT NO.	SEE J.O.	NO. REQD	
DATE ISSD	-		
DEL TO		DATE REQD	-
SURFACE TREATMT			
IDENT METHOD	TAG		
PROJECT NUMBER	ATL-IP-ED-0032		
PROJECT NAME	US ATLAS SILICON SUBSYSTEM		
DWG BY	D UKEN	DATE	29-Jun-01
CHK BY	J WIRTH	DATE	
APR BY	E ANDERSSEN	DATE	

US ATLAS SILICON SUBSYSTEM (logo)

ERNEST ORLANDO LAWRENCE
BERKELEY NATIONAL LABORATORY
UNIVERSITY OF CALIFORNIA - BERKELEY

ATLAS PIXEL DETECTOR
DISK SECTOR, MODULE LOCAL SUPPORT
CORE, SECTOR FOAM/(Cyanate_Ester_for_Foam)

MICROFILMED:	DWG. TYPE	SHOWN ON	SCALE: 1.000	DO NOT SCALE PRINTS
	PART	21F350	SHEET 1 OF 1	
PATENT CLEAR:	DESIGN ACCT. NO.	CATEGORY CODE	DWG. NO.	SIZE / REV.
	SEE J.O.	AP6110	21F3563	1

Dwg. File: 21F356 Model File: 21F356

DWG. NO. 21F3563 SIZE 1 REV. 1 SH. 1

Rev 1/16/2001 ATLAS